

APAC Innovation Summit 2014

Shaping The Future

To mark the 10th anniversary of InnoAsia — the signature event of Hong Kong Science and Technology Parks Corporation — it has been renamed as the APAC Innovation Summit (AIS) with “Shaping the Future” as the theme. With the support of Hong Kong’s universities, R&D centres and over 70 trade associations, AIS aims to create a landmark forum where leading minds and influencers from Asian Pacific nations can converge to mutually inspire through new thinking models and engage in forward-thinking dialogue on policy implementation and market adaption with uniquely Asian characteristics.

Theme: Shaping the Future
Date: 1- 6 Dec 2014 (Mon – Sat)
Time: 9am-6pm
Venue: Hong Kong Convention and Exhibition Centre
Organiser: Hong Kong Science and Technology Parks Corporation
Website: <http://www.apacinnosummit.net/>
Email: info@apacinnosummit.net

Special package for members of Supporting Organisations:

20% discount for members

(Register before 31 October 2014 to enjoy an additional 20% discount on top of the 15% early bird discount)

「亞太創新峰會 2014」 創新締造未來

為慶祝香港科技園公司每年一度的盛事「創新科技亞洲會議」邁入第十年，本屆活動將重新命名為「亞太創新峰會」，以「創新締造未來」為主題，規模更勝歷屆。「亞太創新峰會」已邀請香港大專院校、研發中心及超過70個商會贊助與支持，旨在開創一個具標誌性的論壇，讓來自亞太國家的業界領袖及翹楚互相交流創新思維，並就政策實施及市場應變等議題展開獨具亞洲特色的深入討論。

主題: 創新締造未來
日期: 2014年12月1-6日(星期一至六)
時間: 上午9時至下午6時
地點: 香港會議展覽中心
主辦單位: 香港科技園公司
網頁: <http://www.apacinnosummit.net/>
電郵: info@apacinnosummit.net

支持機構會員報名優惠:

凡支持機構之會員可享 8 折優惠

(於 10 月 31 日前報名，可享 85 折提早報名優惠，支持機構之會員可額外享 8 折優惠)